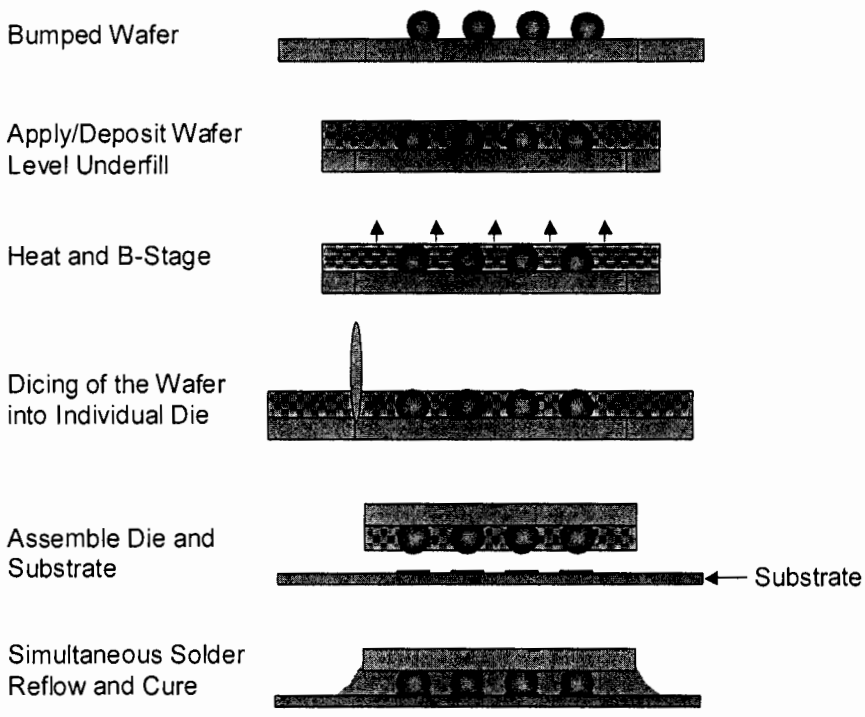


FIGURE 1: Current Pre-Applied Assembly Process

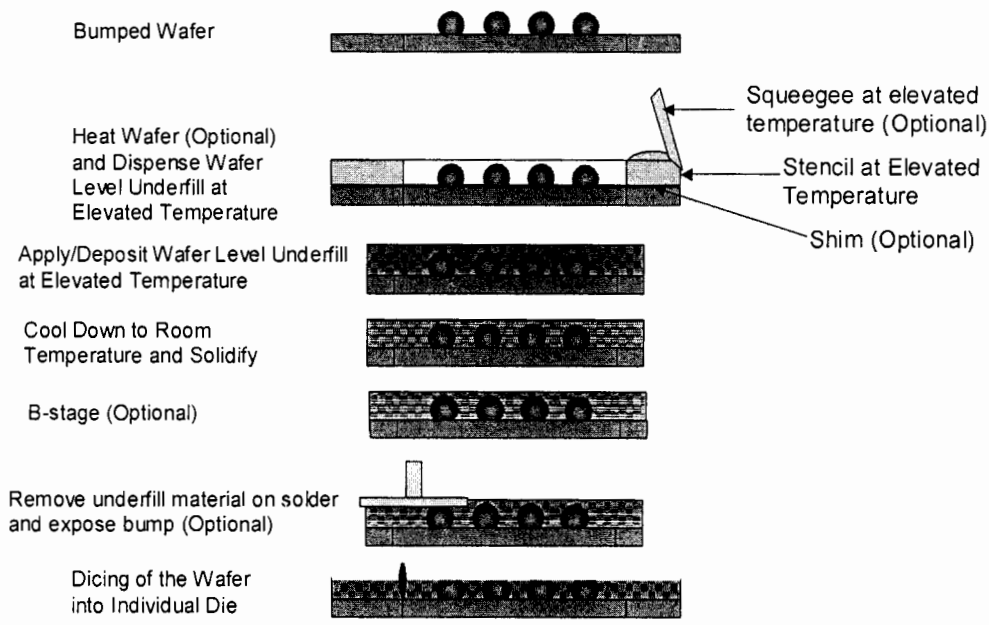


FIGURE 2: Hot Melt Printing Process and Removal of Underfill to Expose Bumps

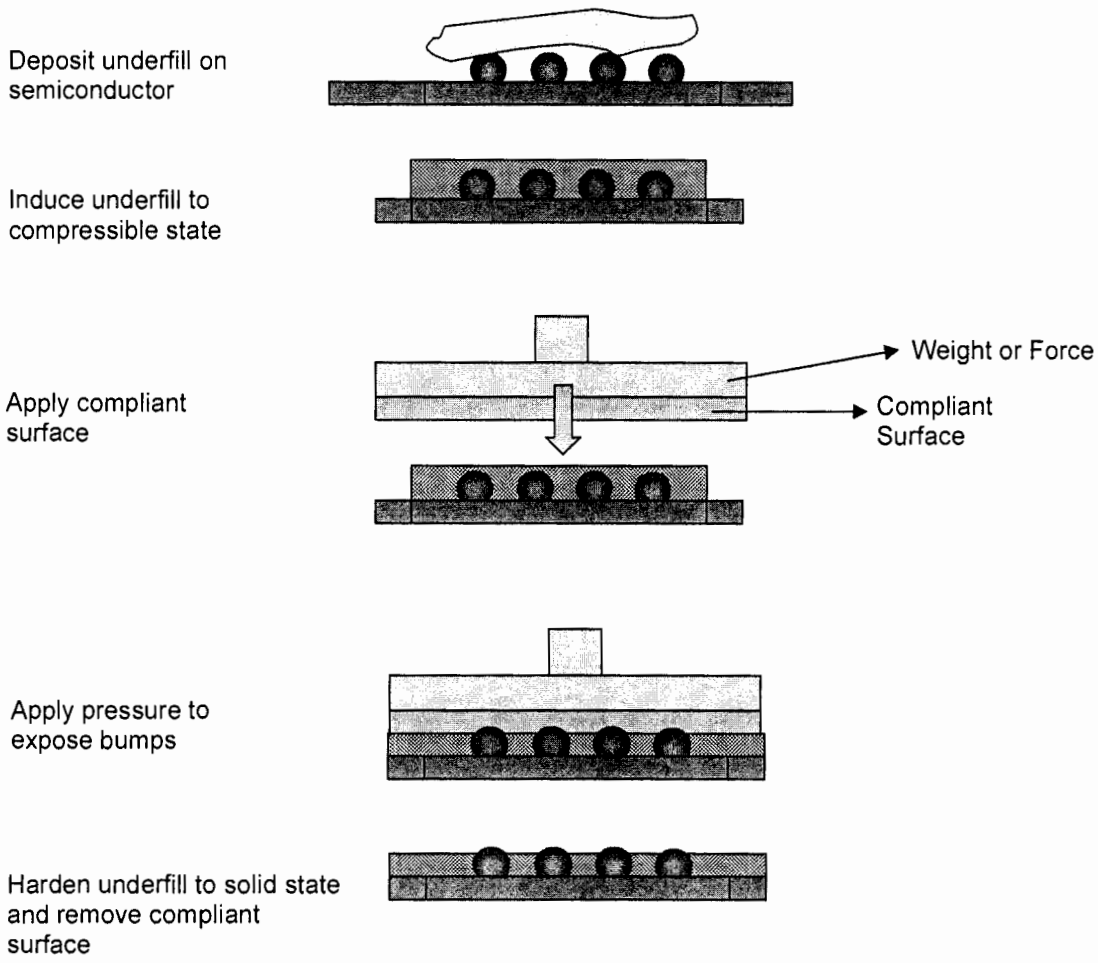


FIGURE 3: Inventive underfill application process

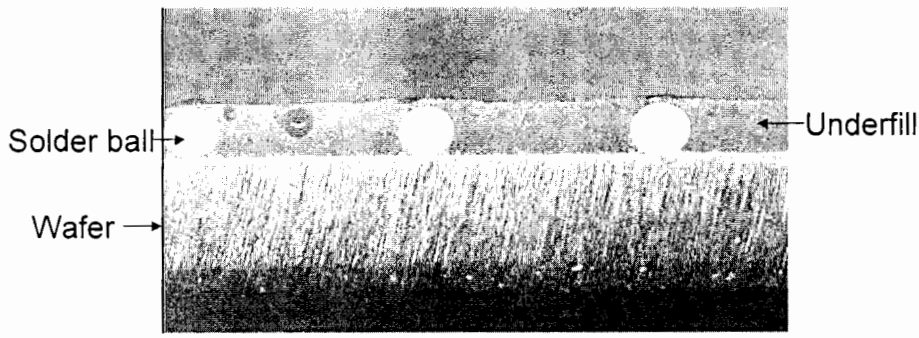


FIGURE 4: Example 1 cross-section,
hot print method

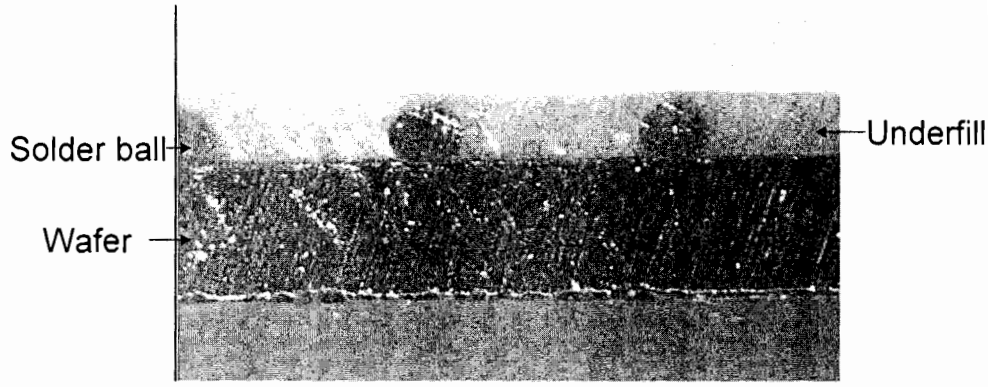


FIGURE 5: Example 2 cross-section,
hot powder coating method

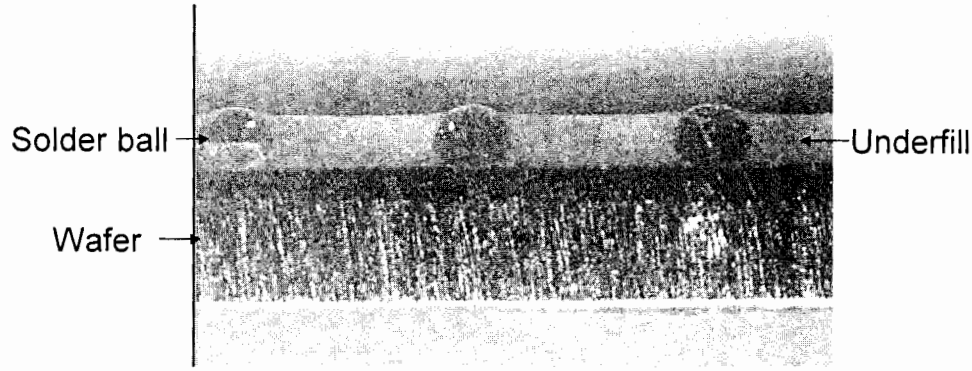


FIGURE 6: Example 3 cross-section, inventive process

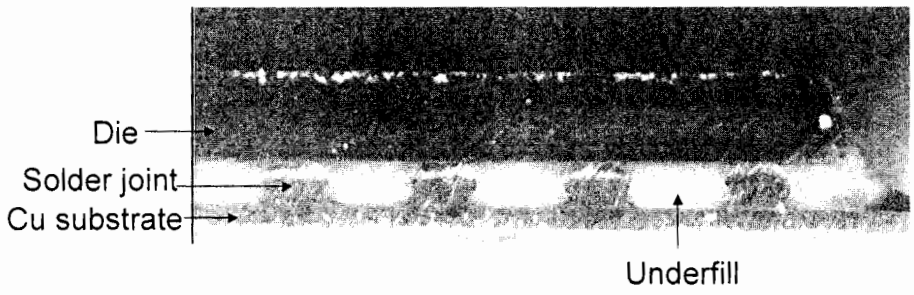


FIGURE 7: Example 4 cross section,
inventive process attached to substrate